

General Description

The WSK330N04G6 advanced SGT technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V.

This device is suitable for use as a Battery protection or in other Switching application.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% E_{AS} Guaranteed
- Green Device Available

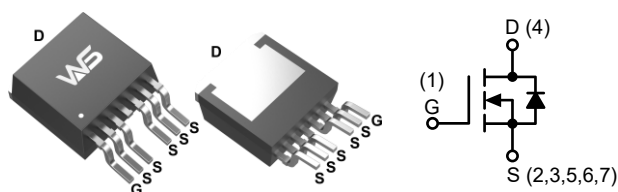
Product Summary

| BV_{DSS} | $R_{DS(ON)}$ | I_D |
|------------|---------------|-------|
| 40V | 1.0m Ω | 330A |

Applications

- Battery protection
- Load switch.
- Uninterruptible power supply

TO-263-6L Pin Configuration



Absolute Maximum Ratings

| Symbol | Parameter | Rating | Units |
|-----------------------|--|------------|------------|
| V_{DS} | Drain-Source Voltage | 40 | V |
| V_{GS} | Gate-Source Voltage | ± 20 | |
| $I_D@T_C=25^\circ C$ | Continuous Drain Current, $V_{GS} @ 10V$ | 330 | A |
| $I_D@T_C=100^\circ C$ | Continuous Drain Current, $V_{GS} @ 10V$ | 212 | |
| I_{DM} | Pulsed Drain Current ² | 528 | |
| E_{AS} | Single Pulse Avalanche Energy ³ | 1125 | mJ |
| I_{AS} | Avalanche Current | 150 | A |
| $P_D@T_C=25^\circ C$ | Total Power Dissipation ⁴ | 125 | W |
| T_{STG} | Storage Temperature Range | -55 to 150 | $^\circ C$ |
| T_J | Operating Junction Temperature Range | -55 to 150 | |

Thermal Data

| Symbol | Parameter | Rating | Units |
|-----------------|--|--------|--------------|
| $R_{\theta JA}$ | Thermal Resistance Junction-Ambient ¹ | 50 | $^\circ C/W$ |
| $R_{\theta JC}$ | Thermal Resistance Junction-Case ¹ | 1.0 | |

Electrical Characteristics ($T_J=25^{\circ}\text{C}$, Unless Otherwise Noted)

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Units |
|------------------------------|--|---|------|-------|-----------|-----------------------|
| BV_{DSS} | Drain-Source Breakdown Voltage | $V_{GS}=0V$, $I_D=250\mu A$ | 40 | --- | --- | V |
| $\Delta BV_{DSS}/\Delta T_J$ | BV_{DSS} Temperature Coefficient | Reference to 25°C , $I_D=1mA$ | --- | 0.043 | --- | $V/^{\circ}\text{C}$ |
| $R_{DS(ON)}$ | Static Drain-Source On-Resistance ² | $V_{GS}=10V$, $I_D=25A$ | --- | 1.0 | 1.5 | m Ω |
| | | $V_{GS}=4.5V$, $I_D=15A$ | --- | 1.5 | 2.1 | |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{GS}=V_{DS}$, $I_D=250\mu A$ | 1.0 | 1.8 | 2.5 | V |
| $\Delta V_{GS(th)}$ | $V_{GS(th)}$ Temperature Coefficient | | --- | -6.94 | --- | $mV/^{\circ}\text{C}$ |
| I_{DSS} | Drain-Source Leakage Current | $V_{DS}=32V$, $V_{GS}=0V$, $T_J=25^{\circ}\text{C}$ | --- | --- | 2.0 | μA |
| | | $V_{DS}=32V$, $V_{GS}=0V$, $T_J=55^{\circ}\text{C}$ | --- | --- | 10 | |
| I_{GSS} | Gate-Body Leakage Current | $V_{GS}=\pm 20V$, $V_{DS}=0V$ | --- | --- | ± 100 | nA |
| g_{fs} | Forward Transconductance | $V_{DS}=10V$, $I_D=15A$ | --- | 47 | --- | S |
| Q_g | Total Gate Charge | $V_{DS}=20V$, $V_{GS}=10V$, $I_D=20A$ | --- | 50 | --- | nC |
| Q_g | Total Gate Charge | $V_{DS}=20V$, $V_{GS}=4.5V$, $I_D=20A$ | --- | 23 | --- | nC |
| Q_{gs} | Gate-Source Charge | | --- | 9.6 | --- | |
| Q_{gd} | Gate-Drain Charge | | --- | 8.7 | --- | |
| $T_{d(on)}$ | Turn-on Delay Time | $V_{DD}=20V$, $V_{GS}=10V$, $R_L=20\Omega$, $R_G=16\Omega$, $I_D=1A$ | --- | 18 | --- | ns |
| T_r | Rise Time | | --- | 10 | --- | |
| $T_{d(off)}$ | Turn-off Delay Time | | --- | 57 | --- | |
| T_f | Fall Time | | --- | 51 | --- | |
| C_{iss} | Input Capacitance | $V_{DS}=20V$, $V_{GS}=0V$, $f=1.0MHz$ | --- | 9500 | --- | pF |
| C_{oss} | Output Capacitance | | --- | 4500 | --- | |
| C_{rss} | Reverse Transfer Capacitance | | --- | 3200 | --- | |

Diode Characteristics

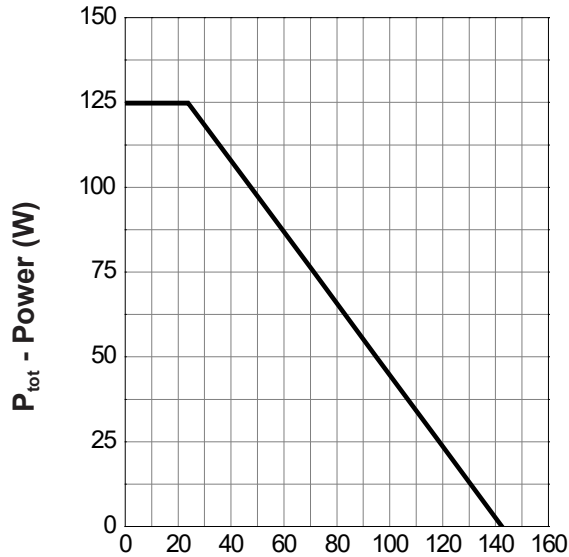
| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Units |
|----------|--|--|------|------|------|-------|
| I_S | Continuous Source Current ^{1,5} | $V_G=V_D=0V$, Force Current | --- | --- | 200 | A |
| V_{SD} | Diode Forward Voltage ² | $V_{GS}=0V$, $I_S=25A$, $T_J=25^{\circ}\text{C}$ | --- | --- | 1.3 | V |

Note:

1. The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper.
2. The data tested by pulsed, pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
3. The E_{AS} data shows Max. rating. The test condition is $V_{DD}=20V$, $V_{GS}=10V$, $L=0.1mH$, $I_{AS}=150A$
4. The power dissipation is limited by 150°C junction temperature.
5. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.

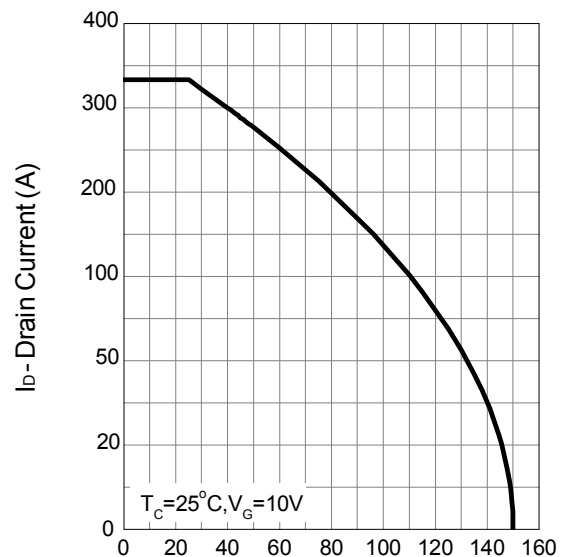
Typical Characteristics

Power Dissipation



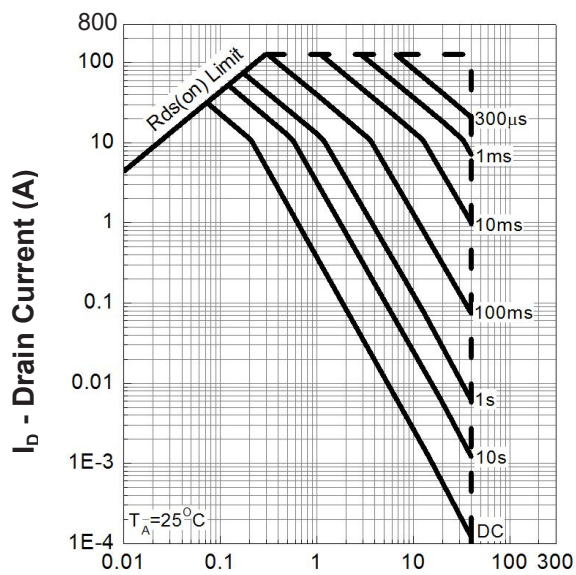
T_c - Case Temperature (°C)

Drain Current



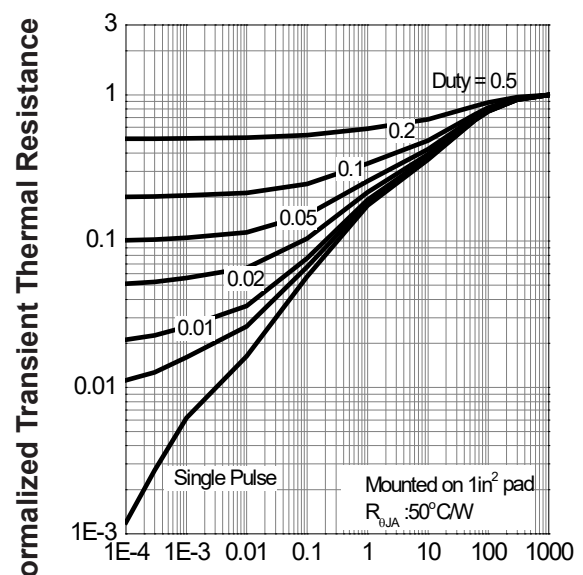
T_j - Junction Temperature (°C)

Safe Operation Area



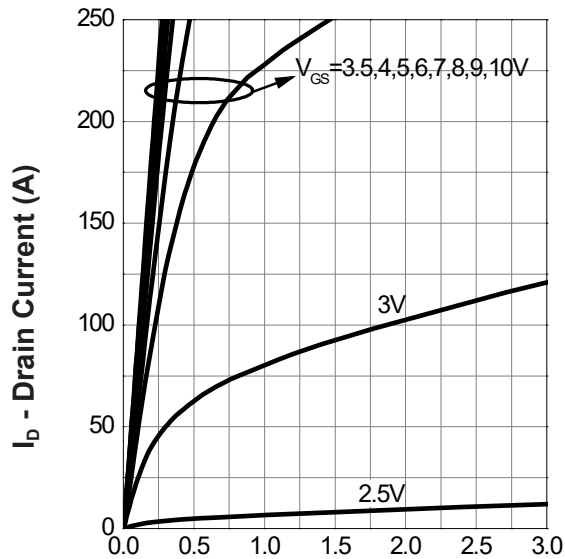
V_{DS} - Drain - Source Voltage (V)

Thermal Transient Impedance

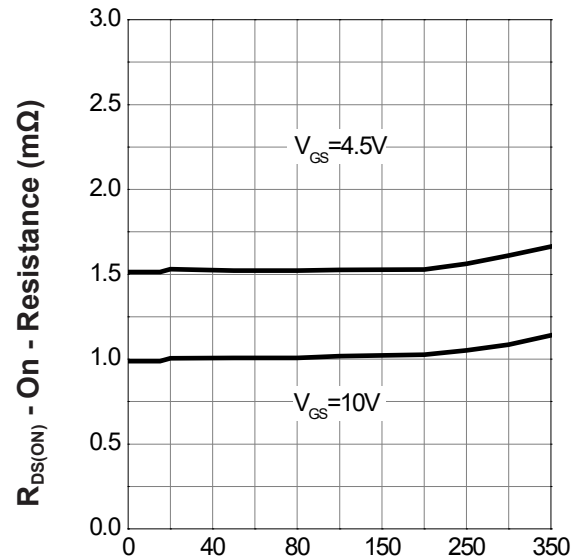


Square Wave Pulse Duration (sec)

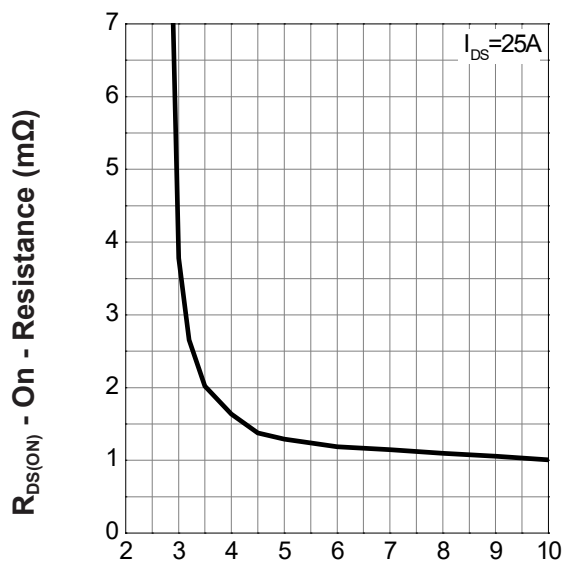
Typical Characteristics (Cont.)

Output Characteristics


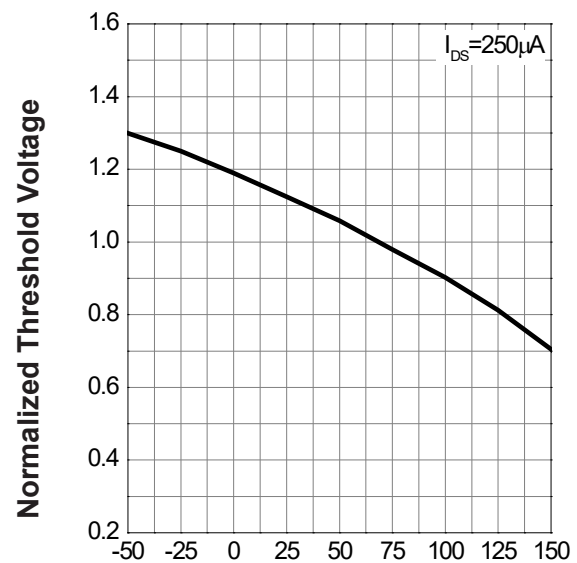
V_{DS} - Drain - Source Voltage (V)

Drain-Source On Resistance


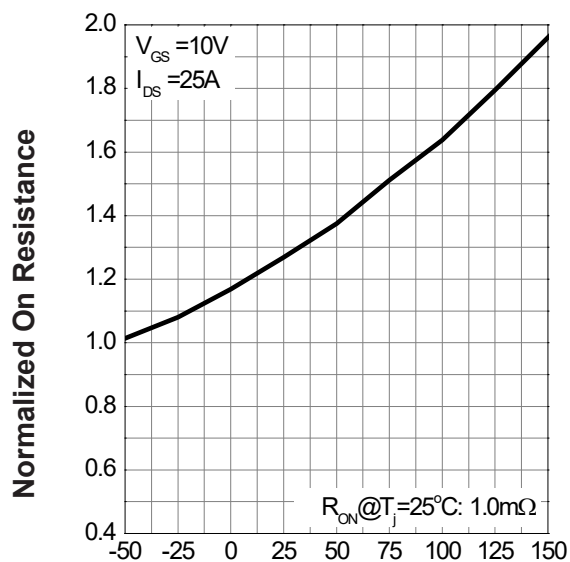
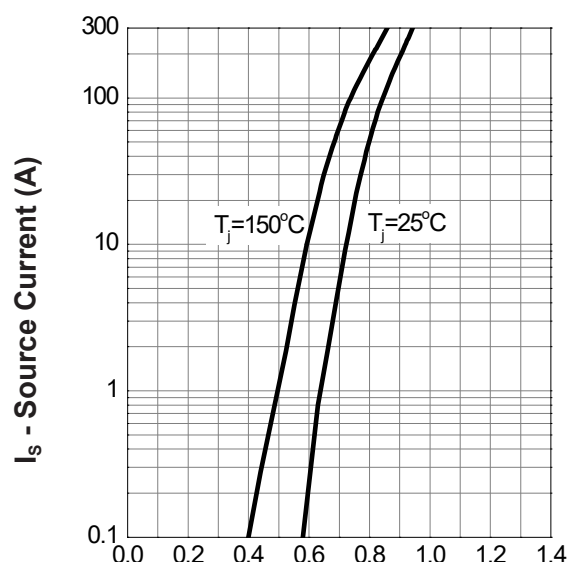
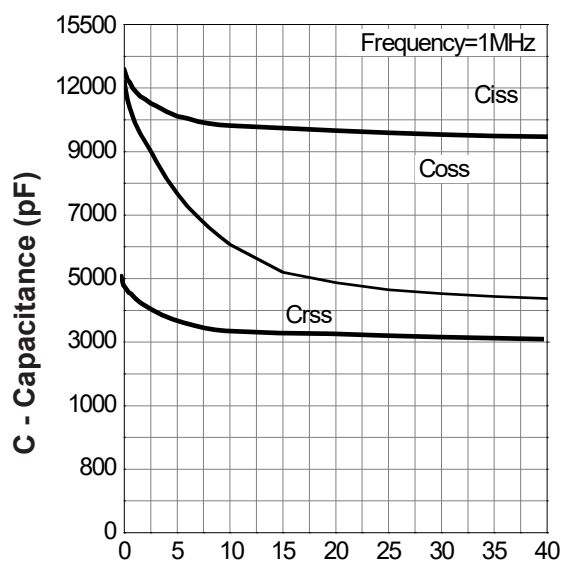
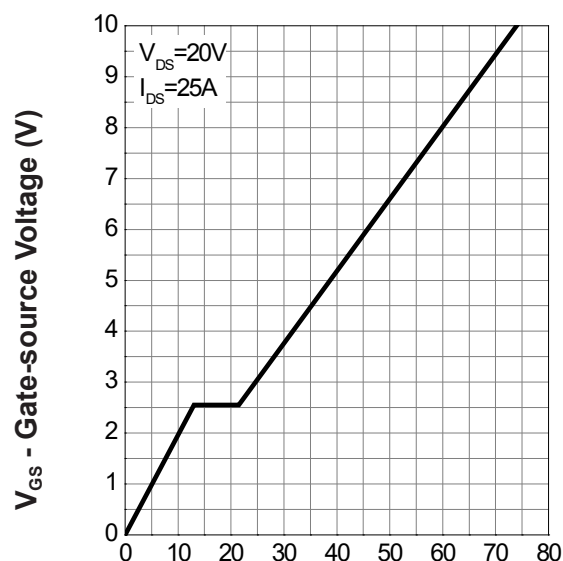
I_D - Drain Current (A)

Gate-Source On Resistance


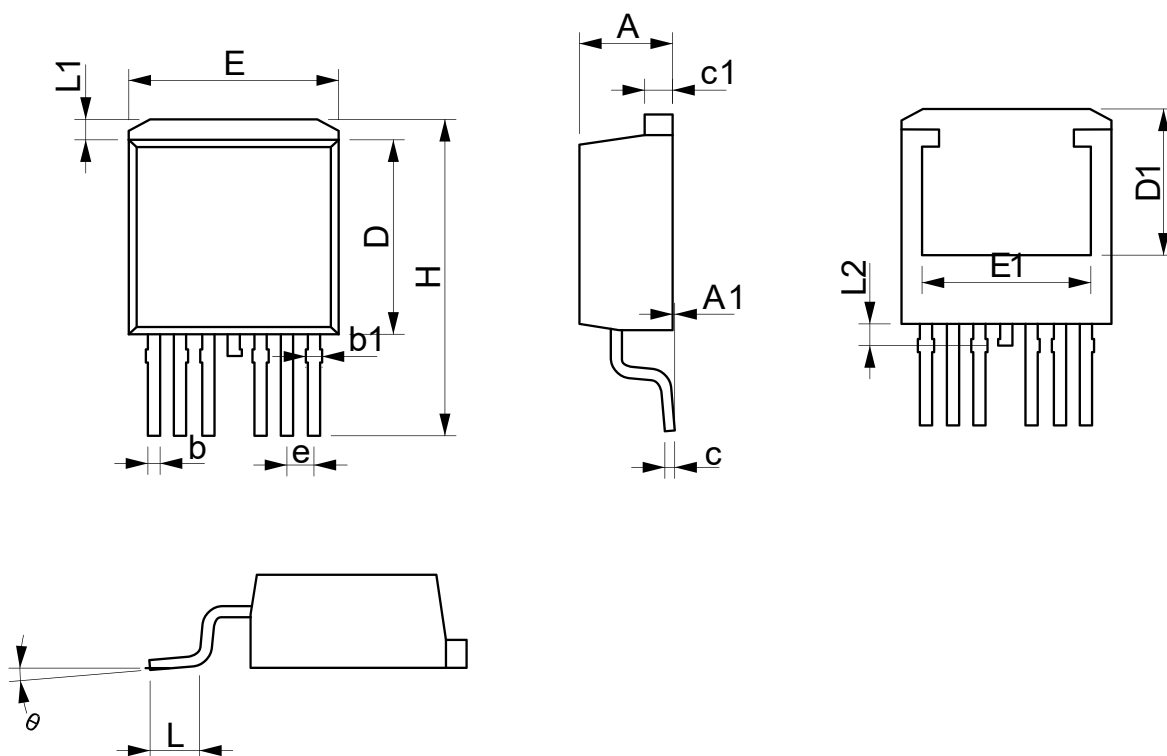
V_{GS} - Gate - Source Voltage (V)

Gate Threshold Voltage


T_j - Junction Temperature (°C)

Typical Characteristics (Cont.)
Drain-Source On Resistance

Source-Drain Diode Forward

Capacitance

Gate Charge


Packaging information



| SYMBOL | MILLIMETERS | | INCHES | |
|--------|-------------|-------|----------|-------|
| | MIN. | MAX. | MIN. | MAX. |
| A | 4.25 | 4.55 | 0.167 | 0.179 |
| A1 | 0.01 | 0.25 | 0.000 | 0.010 |
| b | 0.50 | 0.70 | 0.020 | 0.028 |
| b1 | 0.60 | 0.84 | 0.024 | 0.033 |
| c | 0.40 | 0.60 | 0.016 | 0.024 |
| c1 | 1.20 | 1.40 | 0.047 | 0.055 |
| D | 9.05 | 9.45 | 0.356 | 0.372 |
| D1 | 6.90 | 9.00 | 0.272 | 0.354 |
| E | 9.80 | 10.20 | 0.386 | 0.402 |
| E1 | 7.25 | 9.00 | 0.285 | 0.354 |
| e | 1.27 BSC | | 0.05 BSC | |
| H | 14.65 | 15.35 | 0.577 | 0.604 |
| L | 2.40 | 3.00 | 0.094 | 0.118 |
| L1 | 0.80 | 1.20 | 0.031 | 0.047 |
| L2 | 0.85 | 1.15 | 0.330 | 0.045 |
| θ | 2° | 8° | 2° | 8° |

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